

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SANG IL KIM	04/03/2017
SEUNG WAN KIM	04/03/2017
RECEIVING PARTY DATA	
Name:	HYUNDAI MOTOR COMPANY
Street Address:	12, HEOLLEUNG-RO, SEOCHO-GU
City:	SEOUL
State/Country:	KOREA, REPUBLIC OF
Postal Code:	06797
Name:	KIA MOTORS CORPORATION
Street Address:	12, HEOLLEUNG-RO, SEOCHO-GU
City:	SEOUL
State/Country:	KOREA, REPUBLIC OF
Postal Code:	06797
Name:	PYEONG HWA AUTOMOTIVE CO., LTD.
Street Address:	392, SEONGSEO4CHA CHEOMDAN-RO, DALSEO-GU
City:	DAEGU
State/Country:	KOREA, REPUBLIC OF
Postal Code:	42724
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15499090
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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PATENT

ATTORNEY DOCKET NUMBER:	060943-5446-US
NAME OF SUBMITTER:	SHEILA R. GLOSS
SIGNATURE:	/Sheila R. Gloss/
DATE SIGNED:	04/27/2017
Total Attachments: 2 source=060943-5446-US_Assign#page1.tif source=060943-5446-US_Assign#page2.tif	

ASSIGNMENT
(Joint Inventors)

WHEREAS, the undersigned, (1) **KIM, Sang Il**, resident of (Sibeom Gyeryong Rishubil Apt.) 924-1301, 236, Dongtandaerosibeom-gil, Hwaseong-si, Gyeonggi-do, 18477, Republic of Korea, and (2) **KIM, Seung Wan**, resident of (Keumsungvil) 203, 72-5, World cup-ro 193beon-gil, Yeongtong-gu, Suwon-si, Gyeonggi-do, 16502, Republic of Korea (hereinafter termed "Inventors"), respectively, have invented certain new and useful improvements in *HOOD HINGE APPARATUS FOR VEHICLE* and executed therefore an application for Letters Patent of the United States and

- having an oath or declaration executed on even date herewith.
 bearing U.S. Patent Application No. _____ and filed on _____.

WHEREAS, **Hyundai Motor Company**, a corporation of the Republic of Korea, having a place of business at 12, Heolleung-ro, Seocho-gu, Seoul, 06797, Republic of Korea, **Kia Motors Corporation**, a corporation of the Republic of Korea, having a place of business at 12, Heolleung-ro, Seocho-gu, Seoul, 06797, Republic of Korea, **PYEONG HWA AUTOMOTIVE CO., LTD.**, a corporation of the Republic of Korea, having a place of business at 392, Seongseo4chacheomdan-ro, Dalseo-gu, Daegu, 42724, Republic of Korea (hereinafter termed "Assignee"), is desirous of acquiring the entire right, title and interest of said Inventors in and to said application and the invention disclosed therein, and in and to all embodiments of the invention, heretofore conceived, made or discovered jointly or severally by said Inventors (all collectively hereinafter termed "said invention"), and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter termed "patents") thereon granted in the United States and foreign countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Inventors to have been received in full from said Assignee:

1. Said Inventors do hereby sell, assign, transfer and convey unto said Assignee, the entire right, title and interest (a) in and to said application and said invention; (b) in and to all rights to apply for foreign patents on said invention pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all applications filed and any and all patents granted on said invention in the United States or any foreign country, including each and every application filed and each and every patent granted on any application which is a division, substitution, or continuation of any of said applications; and (d) in and to each and every reissue or extensions of any of said patents.

2. Said Inventors do hereby jointly and severally covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right title and interest herein conveyed in the United States and foreign countries. Such cooperation by said Inventors shall include prompt production of pertinent facts and documents, giving of testimony, execution of petitions, oaths, specifications, declarations or other papers, and other

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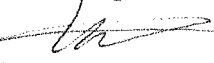
Attorney Docket No. _____

assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said invention; (d) for filing and prosecuting applications for reissuance of any said patents; (e) for interference or other priority proceedings involving said invention; and (f) for legal proceedings involving said invention and any applications therefor and any patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Inventors in providing such cooperation shall be paid for by said Assignee.

3. The terms and covenants of this assignment shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Inventors, their respective heirs, legal representatives and assigns.

4. Said Inventors do hereby jointly and severally warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Inventors have executed and delivered this instrument to said Assignee as follows:

Date: April 3, 2017 (1) **KIM, Sang Il**
By: 

Date: April 3, 2017 (2) **KIM, Seung Wan**
By: 